MSKSEMI















ESD

TVS

TSS

MOV

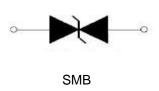
GDT

PLED

Broduct data sheet







Features

Low capatcitance
Cannot be damaged by voltage
Will not fatigue
Eliminate voltage overshoot
Glass passivated junction
Halogen free and RoHS compliant

Mechanical Data

CASE: SMB(DO-214AA) Molded Plastic UL Flammability Classification Rating 94V0 Mounting Position:Any

Maximum Ratings & Thermal Characteristics

(Ratings at 25°C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Units	Remarks
Peak Pulse Voltage	V _{PP}	6000	V	10/700us
Peak Pulse Current	lpp	100	А	10/1000u s
Peak Pulse Current	I _{PK}	400	Α	8/20us
Peak One-cycle Surge Current	I _{TSM}	30	А	60Hz
Rate of Rise of Current	di/dt	500	A/us	
Typical Thermal Resistance Junction to Lead	R _{θJL}	20	°C/W	
Typical Thermal Resistance Junction to Ambient	$R_{ heta JA}$	100	°C/W	
Operating Temperature Range	TJ	-40 to 150	°C	
Storage Temperature Range	T _{STG}	-55 to 150	°C	



Electrical Characteristics

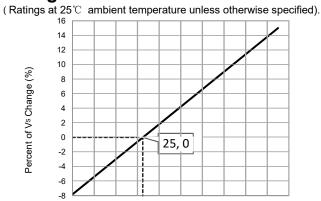
(Ratings at 25 °C ambient temperature unless otherwise specified).

Part		V _S @100KV/S	I _{S_LMT}	V _T @ I _⊺	Ι _Τ	I _D @ V _D	V _D	C _O @1MHz,2V _{DC}	I _H
Number	Marking	V MAX	mA	V MAX	А	uA MAX	V	pF TYP	mA MIN
P0080SC-MS	E-8C XXXX	25	500	4	2.2	5	6	105	40
P0220SC-MS	P02C XXXX	30	500	4	2.2	5	15	105	40
P0300SC-MS	P03C XXXX	40	500	4	2.2	5	25	100	40
P0640SC-MS	P06C XXXX	77	800	4	2.2	5	58	95	120
P0720SC-MS	P07C XXXX	88	800	4	2.2	5	65	95	120
P0900SC-MS	P09C XXXX	98	800	4	2.2	5	75	95	120
P1100SC-MS	P11C XXXX	130	800	4	2.2	5	90	90	120
P1300SC-MS	P13C XXXX	160	800	4	2.2	5	120	90	120
P1500SC-MS	P15C XXXX	180	800	4	2.2	5	140	85	120
P1800SC-MS	P18C XXXX	220	800	4	2.2	5	170	80	120
P2300SC-MS	P23B XXXX	260	800	4	2.2	5	190	75	120
P2600SC-MS	P26C XXXX	300	800	4	2.2	5	220	70	120
P3100SC-MS	P31C XXXX	350	800	4	2.2	5	275	65	120
P3500SC-MS	P35C XXXX	400	800	4	2.2	5	320	60	120
P4500SC-MS	P45C XXXX	550	800	4	2.2	5	400	45	120



-40

Ratings and Characteristic Curves



 T_J - Junction Temperature (°C) Fig.1 - Peak Pulse Current Rating

20 40 60 80 100 120 140 160

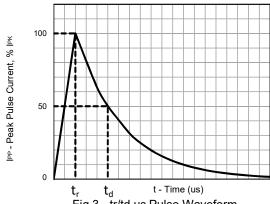


Fig.3 - tr/td us Pulse Waveform 10000 1000 IPP - Peak Pulse Current (A) 100 10 0.1 1000 td - Pulse Width (us)

Fig.5 - Peak Pulse Current Rating

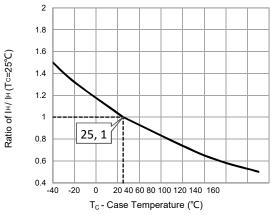
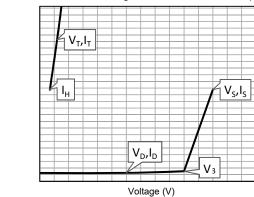
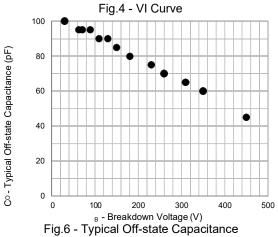


Fig.2 - Normalized DC Holding Current vs. Case Temperature

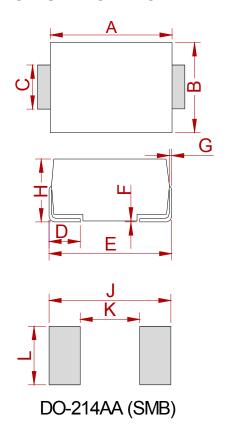


Current (A)





PACKAGE MECHANICAL DATA



	Dimensions					
Ref.	Millir	neters	Inches			
	Min.	Max.	Min.	Max.		
Α	4.25	4.75	0.167	0.187		
В	3.30	3.94	0.130	0.155		
С	1.85	2.21	0.073	0.087		
D	0.76	1.52	0.030	0.060		
Е	5.08	5.59	0.200	0.220		
F	0.051	0.203	0.002	0.008		
G	0.15	0.31	0.006	0.012		
Н	2.11	2.44	0.083	0.096		
J	6.80		0.270			
K		2.60		0.100		
L	2.40		0.090			

REEL SPECIFICATION

P/N	PKG	QTY
PxxxxSC-MS	SMB	3000



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